Driver Transistors

NPN Silicon

Features

 These Devices are Pb-Free, Halogen Free/BFR Free and are RoHS Compliant

MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Collector – Emitter Voltage MMBTA05LT1 MMBTA06LT1	V _{CEO}	60 80	Vdc
Collector - Base Voltage MMBTA05LT1 MMBTA06LT1	V _{CBO}	60 80	Vdc
Emitter – Base Voltage	V _{EBO}	4.0	Vdc
Collector Current - Continuous	Ic	500	mAdc

THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Total Device Dissipation FR-5 Board (Note 1) T _A = 25°C Derate above 25°C	P _D	225 1.8	mW mW/°C
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	556	°C/W
Total Device Dissipation Alumina Substrate, (Note 2) T _A = 25°C Derate above 25°C	P _D	300 2.4	mW mW/°C
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	417	°C/W
Junction and Storage Temperature	T _J , T _{stg}	-55 to +150	°C

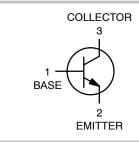
Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

- 1. FR-5 = $1.0 \times 0.75 \times 0.062$ in.
- 2. Alumina = $0.4 \times 0.3 \times 0.024$ in. 99.5% alumina.



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SOT-23 CASE 318 STYLE 6

MARKING DIAGRAMS





MMBTA05LT1

MMBTA06LT1

1H, 1GM = Specific Device Code

M = Date Code*
= Pb-Free Package

(Note: Microdot may be in either location)
*Date Code orientation and/or overbar may
vary depending upon manufacturing location.

ORDERING INFORMATION

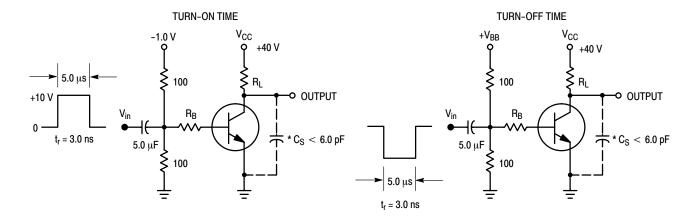
See detailed ordering and shipping information in the package dimensions section on page 4 of this data sheet.

ELECTRICAL CHARACTERISTICS (T_A = 25°C unless otherwise noted)

Characteristic		Symbol	Min	Max	Unit
OFF CHARACTERISTICS		-			ı
Collector – Emitter Breakdown Voltage (Note 3) $(I_C = 1.0 \text{ mAdc}, I_B = 0)$	MMBTA05 MMBTA06	V _{(BR)CEO}	60 80	_ _	Vdc
Emitter – Base Breakdown Voltage ($I_E = 100 \mu Adc, I_C = 0$)		V _{(BR)EBO}	4.0	-	Vdc
Collector Cutoff Current (V _{CE} = 60 Vdc, I _B = 0)		I _{CES}	-	0.1	μAdc
Collector Cutoff Current $(V_{CB} = 60 \text{ Vdc}, I_E = 0)$ $(V_{CB} = 80 \text{ Vdc}, I_E = 0)$	MMBTA05 MMBTA06	I _{CBO}	- -	0.1 0.1	μAdc
ON CHARACTERISTICS					
DC Current Gain $ (I_C = 10 \text{ mAdc}, V_{CE} = 1.0 \text{ Vdc}) $ $ (I_C = 100 \text{ mAdc}, V_{CE} = 1.0 \text{ Vdc}) $		h _{FE}	100 100	- -	-
Collector – Emitter Saturation Voltage (I _C = 100 mAdc, I _B = 10 mAdc)		V _{CE(sat)}	-	0.25	Vdc
Base – Emitter On Voltage (I _C = 100 mAdc, V _{CE} = 1.0 Vdc)		V _{BE(on)}	-	1.2	Vdc
SMALL-SIGNAL CHARACTERISTICS		•	-	•	•
Current – Gain – Bandwidth Product (Note 4) $(I_C = 10 \text{ mA}, V_{CE} = 2.0 \text{ V}, f = 100 \text{ MHz})$		f _T	100	_	MHz

^{3.} Pulse Test: Pulse Width \leq 300 μ s, Duty Cycle \leq 2.0%.

^{4.} f_T is defined as the frequency at which $|h_{fe}|$ extrapolates to unity.



^{*}Total Shunt Capacitance of Test Jig and Connectors For PNP Test Circuits, Reverse All Voltage Polarities

Figure 1. Switching Time Test Circuits

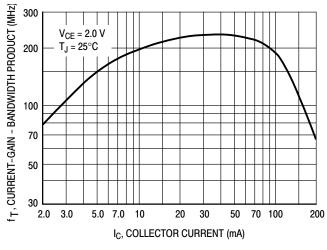


Figure 2. Current-Gain — Bandwidth Product

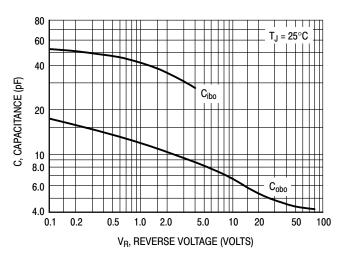


Figure 3. Capacitance

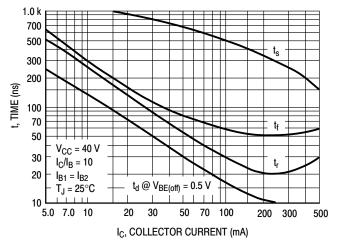


Figure 4. Switching Time

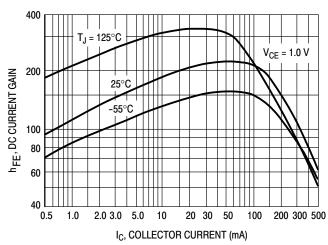


Figure 5. DC Current Gain

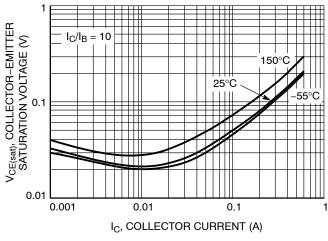


Figure 6. Collector Emitter Saturation Voltage vs. Collector Current

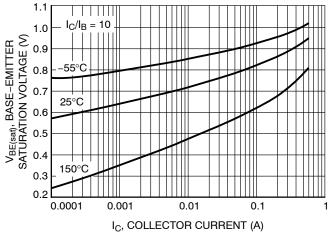


Figure 7. Base Emitter Saturation Voltage vs.
Collector Current

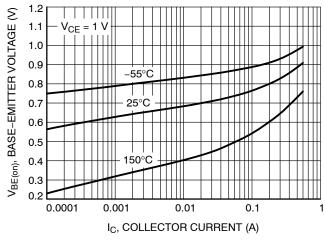


Figure 8. Base Emitter Voltage vs. Collector Current

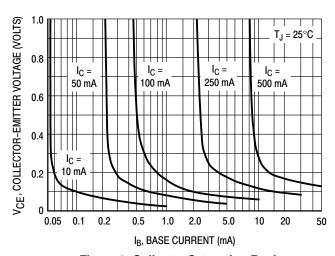


Figure 9. Collector Saturation Region

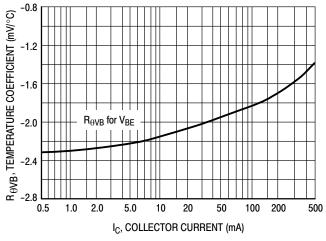


Figure 10. Base–Emitter Temperature Coefficient

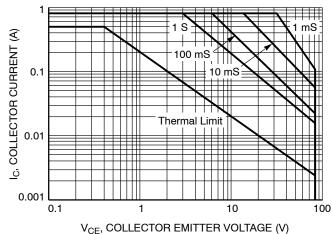


Figure 11. Safe Operating Area

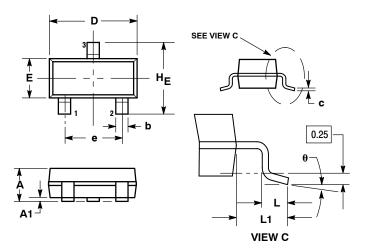
ORDERING INFORMATION

Device	Package	Shipping [†]		
MMBTA05LT1G	SOT-23 (Pb-Free)	3000 / Tape & Reel		
MMBTA05LT3G	SOT-23 (Pb-Free)	10,000 / Tape & Reel		
MMBTA06LT1G	SOT-23 (Pb-Free)	3000 / Tape & Reel		
MMBTA06LT3G	SOT-23 (Pb-Free)	10,000 / Tape & Reel		

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

PACKAGE DIMENSIONS

SOT-23 (TO-236) CASE 318-08 **ISSUE AN**



NOTES:

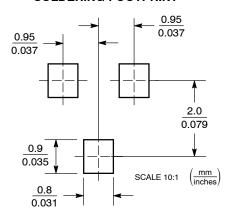
- 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982. 2. CONTROLLING DIMENSION: INCH.
- MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL
- 4. 318-01 THRU -07 AND -09 OBSOLETE, NEW STANDARD

	MILLIMETERS				INCHES	
DIM	MIN	NOM	MAX	MIN	NOM	MAX
Α	0.89	1.00	1.11	0.035	0.040	0.044
A1	0.01	0.06	0.10	0.001	0.002	0.004
b	0.37	0.44	0.50	0.015	0.018	0.020
С	0.09	0.13	0.18	0.003	0.005	0.007
D	2.80	2.90	3.04	0.110	0.114	0.120
E	1.20	1.30	1.40	0.047	0.051	0.055
е	1.78	1.90	2.04	0.070	0.075	0.081
L	0.10	0.20	0.30	0.004	0.008	0.012
L1	0.35	0.54	0.69	0.014	0.021	0.029
HE	2.10	2.40	2.64	0.083	0.094	0.104

STYLE 6:

- PIN 1. BASE 2. EMITT
 - EMITTER
 - COLLECTOR

SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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